

**FEE TRANSMITTAL**

Electronic Version v08

Stylesheet Version v08.0

**Title of  
Invention**

[FLIP-CHIP DIE AND FLIP-CHIP PACKAGE SUBSTRATE]

Application Number :

Date :

First Named Applicant: Mr. Chi-Hsing Hsu

Attorney Docket Number: 8810-US-PA-1

**TOTAL FEE AUTHORIZED \$ 806**

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

**BASIC FILING FEE**

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

**EXTRA CLAIM FEES**

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 22	2	1202	18	36
Independent Claims : 2	0	1201	88	0
Subtotal For Extra Claims Fees: \$ 36				

**AUTHORIZED BILLING INFORMATION****The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Credit account number: 1007  
Expiration Date (YYYYMMDD): 2005-12-31  
Authorized name: YEH, WEN-HUNG  
Billing address: 99999